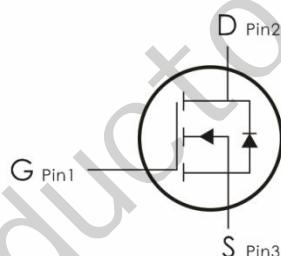
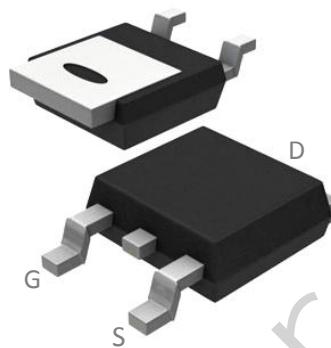


Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=80V, I_D=45A, R_{DS(on)}<20m\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ¹⁾	45	A
$I_{D, \text{pulse}}$	Pulsed drain current ²⁾	135	A
I_S	Continuous diode forward current ¹⁾	45	A
$I_{S, \text{pulse}}$	Diode pulsed current ²⁾	135	A
P_D	Continuous-Source Current ³⁾	75	W
E_{AS}	Single pulsed avalanche energy ⁵⁾	22	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	1.67	°C/W
R_{eJA}	Thermal Resistance,Junction to Ambient ⁴⁾	62	

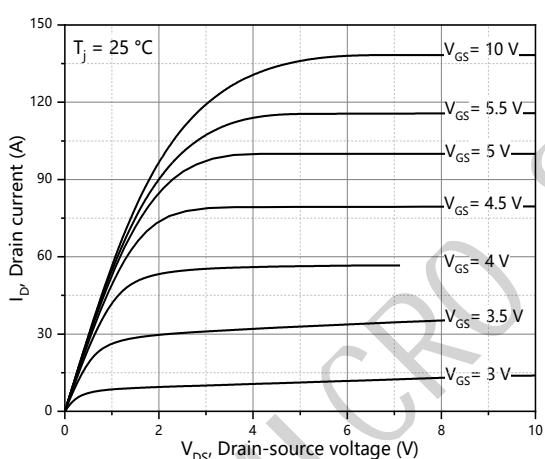
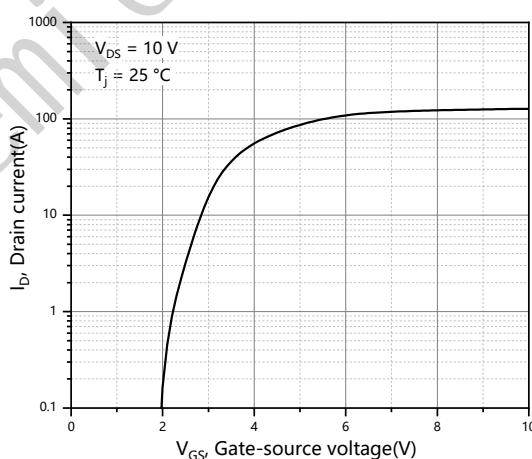
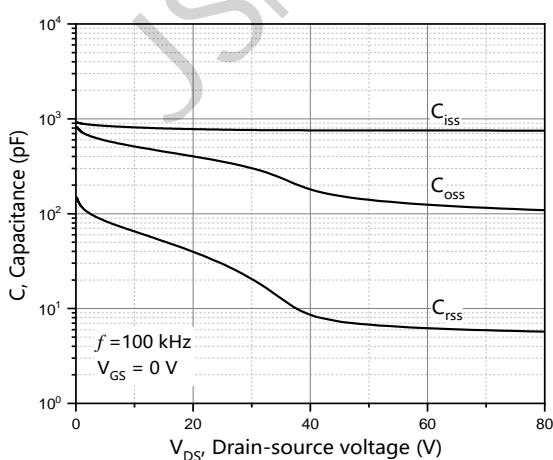
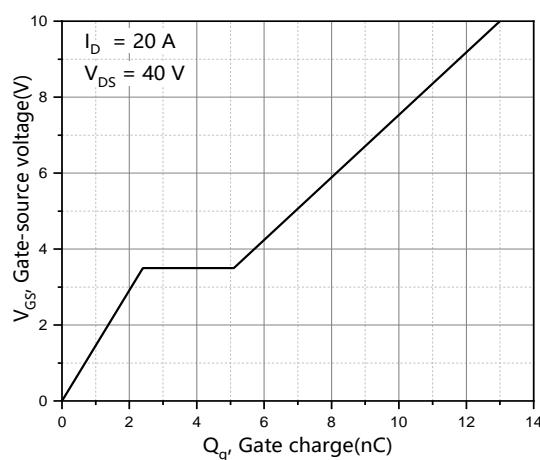
Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	80	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
R_{G}	Gate resistance	$f=1 \text{MHz}, \text{Open drain}$	---	2.9	---	Ω
On Characteristics						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1.0	---	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=12\text{A}$	---	13	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=9\text{A}$	---	17	24	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	760	---	pF
C_{oss}	Output Capacitance		---	340	---	
C_{rss}	Reverse Transfer Capacitance		---	27	---	
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=40\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=2\Omega$	---	16	--	ns
t_r	Rise Time		---	4	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	28	---	ns
t_f	Fall Time		---	5.1	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=40\text{V}, I_{\text{D}}=20\text{A}$	---	12	---	nC
Q_{gs}	Gate-Source Charge		---	2.2	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	2.5	---	nC
V_{plateau}	Gate plateau voltage		---	3.2	---	V
Drain-Source Diode Characteristics						

V_{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V, I _S =20A	---	---	1.3	V
trr	Reverse Recovery Time	V _R =40V, I _S =20 A dI _{SD} /dt = 100 A/ μ s	---	30	---	Ns
qrr	Reverse Recovery Charge			19	---	uc
Irrm	Peak reverse recovery current		---	1	---	A

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Typical Characteristics: (T_c=25 °C unless otherwise noted)

Figure 1. Typ. output characteristics

Figure 2. Typ. transfer characteristics

Figure 3. Typ. capacitances

Figure 4. Typ. gate charge

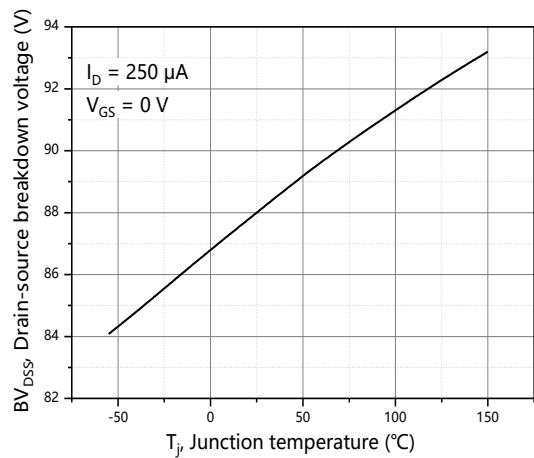


Figure 5. Drain-source breakdown voltage

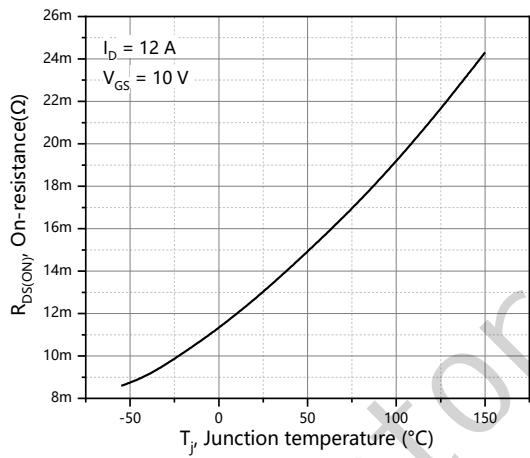


Figure 6. Drain-source on-state resistance

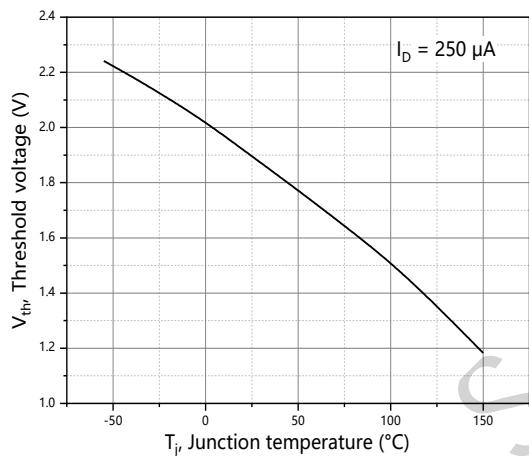


Figure 7. Threshold voltage

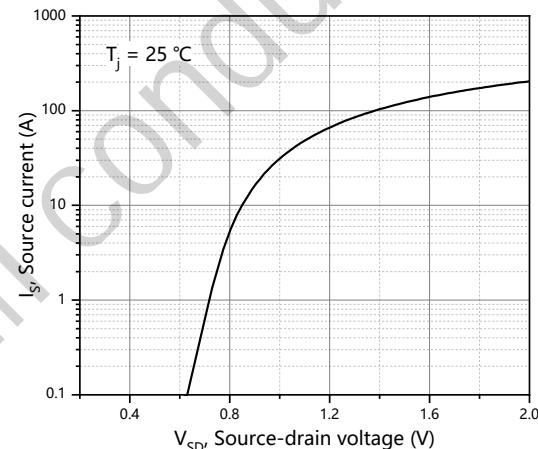


Figure 8. Forward characteristic of body diode

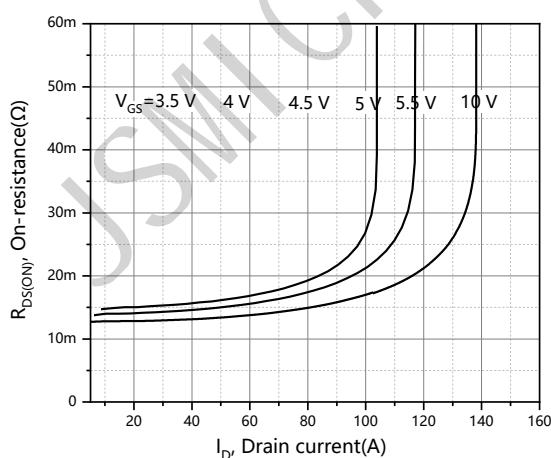


Figure 9. Drain-source on-state resistance

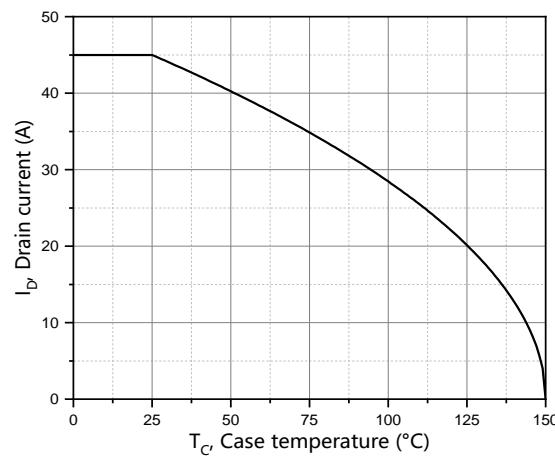


Figure 10. Drain current

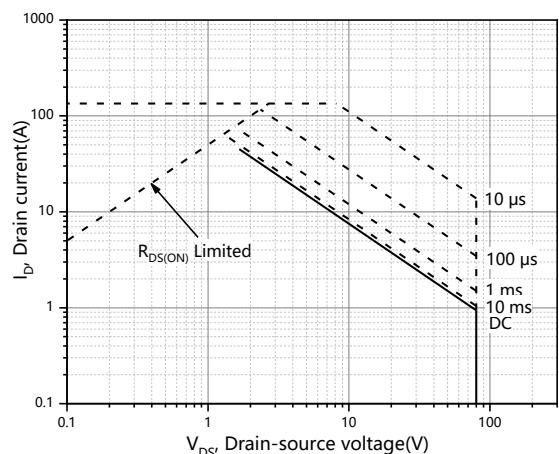


Figure 11. Safe operation area $T_c=25^\circ\text{C}$

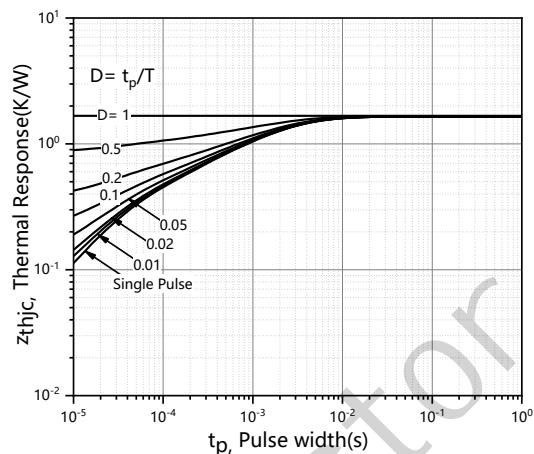
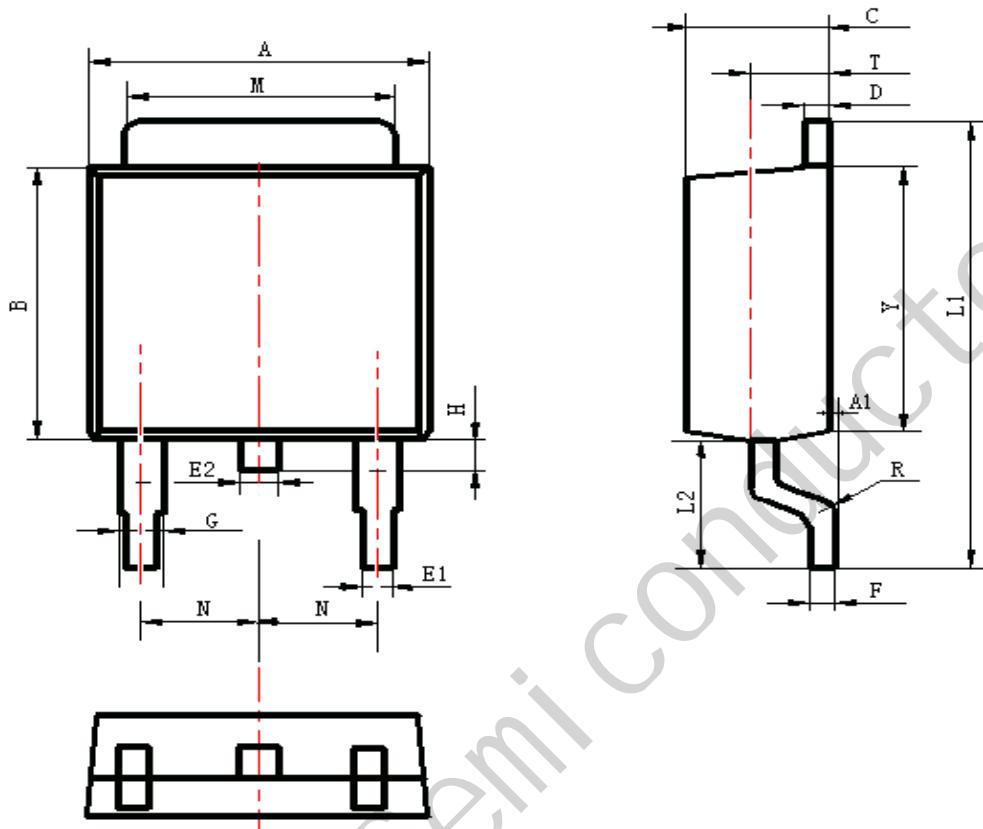


Figure 12. Max. transient thermal impedance

Package Information

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	6.30	6.90	0.248	0.272
A1	0.00	0.16	0.000	0.006
B	5.70	6.30	0.224	0.248
C	2.10	2.50	0.083	0.098
D	0.30	0.70	0.012	0.028
E1	0.60	0.90	0.024	0.035
E2	0.70	1.00	0.028	0.039
F	0.30	0.60	0.012	0.024
G	0.70	1.20	0.028	0.047
L1	9.60	10.50	0.378	0.413
L2	2.70	3.10	0.106	0.122
H	0.40	1.00	0.016	0.039
M	5.10	5.50	0.201	0.217
N	2.09	2.49	0.082	0.098
R	0.30		0.012	
T	1.40	1.60	0.055	0.063
Y	5.10	6.30	0.201	0.248